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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	23780
Number of Logic Elements/Cells	504000
Total RAM Bits	27695104
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxbb7d6f35c6n

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Caution: Conditions outside the range listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 1-1: Absolute Maximum Ratings for Arria V Devices

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Core voltage power supply	-0.50	1.43	V
V _{CCP}	Periphery circuitry, PCIe® hardIP block, and transceiver physical coding sublayer (PCS) power supply	-0.50	1.43	V
V _{CCPGM}	Configuration pins power supply	-0.50	3.90	V
V _{CC_AUX}	Auxiliary supply	-0.50	3.25	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.50	3.90	V
V _{CCPD}	I/O pre-driver power supply	-0.50	3.90	V
V _{CCIO}	I/O power supply	-0.50	3.90	V
V _{CCD_FPLL}	Phase-locked loop (PLL) digital power supply	-0.50	1.80	V
V _{CCA_FPLL}	PLL analog power supply	-0.50	3.25	V
V _{CCA_GXB}	Transceiver high voltage power	-0.50	3.25	V
V _{CCH_GXB}	Transmitter output buffer power	-0.50	1.80	V
V _{CCR_GXB}	Receiver power	-0.50	1.50	V
V _{CCT_GXB}	Transmitter power	-0.50	1.50	V
V _{CCL_GXB}	Transceiver clock network power	-0.50	1.50	V
V _I	DC input voltage	-0.50	3.80	V
V _{CC_HPS}	HPS core voltage and periphery circuitry power supply	-0.50	1.43	V
V _{CCPD_HPS}	HPS I/O pre-driver power supply	-0.50	3.90	V
V _{CCIO_HPS}	HPS I/O power supply	-0.50	3.90	V
V _{CCRSTCLK_HPS}	HPS reset and clock input pins power supply	-0.50	3.90	V

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	$I_{OL}^{(14)}$ (mA)	$I_{OH}^{(14)}$ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	16	-16
HSUL-12	—	$V_{REF} - 0.13$	$V_{REF} + 0.13$	—	$V_{REF} - 0.22$	$V_{REF} + 0.22$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	—	—

Differential SSTL I/O Standards

Table 1-17: Differential SSTL I/O Standards for Arria V Devices

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.62	$V_{CCIO} + 0.6$
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	$V_{CCIO} + 0.6$
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	⁽¹⁵⁾	$V_{CCIO}/2 - 0.15$	—	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$
SSTL-135	1.283	1.35	1.45	0.18	⁽¹⁵⁾	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

⁽¹⁴⁾ To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.

⁽¹⁵⁾ The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits ($V_{IH(DC)}$ and $V_{IL(DC)}$).

- **Transceiver Specifications for Arria V GT and ST Devices** on page 1-29
Provides the specifications for transmitter, receiver, and reference clock I/O pin.

Switching Characteristics

This section provides performance characteristics of Arria V core and periphery blocks.

Transceiver Performance Specifications

Transceiver Specifications for Arria V GX and SX Devices

Table 1-20: Reference Clock Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O standards		1.2 V PCML, 1.4 V PCML, 1.5 V PCML, 2.5 V PCML, Differential LVPECL ⁽²³⁾ , HCSL, and LVDS						
Input frequency from REFCLK input pins	—	27	—	710	27	—	710	MHz
Rise time	Measure at ± 60 mV of differential signal ⁽²⁴⁾	—	—	400	—	—	400	ps
Fall time	Measure at ± 60 mV of differential signal ⁽²⁴⁾	—	—	400	—	—	400	ps
Duty cycle	—	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	300 ⁽²⁵⁾ /2000	200	—	300 ⁽²⁵⁾ /2000	mV

⁽²³⁾ Differential LVPECL signal levels must comply to the minimum and maximum peak-to-peak differential input voltage specified in this table.

⁽²⁴⁾ REFCLK performance requires to meet transmitter REFCLK phase noise specification.

⁽²⁵⁾ The maximum peak-to-peak differential input voltage of 300 mV is allowed for DC coupled link.

Table 1-31: Transceiver-FPGA Fabric Interface Specifications for Arria V GT and ST Devices

Symbol/Description	Transceiver Speed Grade 3		Unit
	Min	Max	
Interface speed (PMA direct mode)	50	153.6 ⁽⁵⁶⁾ , 161 ⁽⁵⁷⁾	MHz
Interface speed (single-width mode)	25	187.5	MHz
Interface speed (double-width mode)	25	163.84	MHz

Related Information

- [CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain](#) on page 1-35
- [CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain](#) on page 1-36

⁽⁵⁶⁾ The maximum frequency when core transceiver local routing is selected.

⁽⁵⁷⁾ The maximum frequency when core transceiver network routing (GCLK, RCLK, or PCLK) is selected.

Table 1-34: Transceiver Compliance Specification for All Supported Protocol for Arria V GX, GT, SX, and ST Devices

Protocol	Sub-protocol	Data Rate (Mbps)
PCIe	PCIe Gen1	2,500
	PCIe Gen2	5,000
	PCIe Cable	2,500
XAUl	XAUl 2135	3,125
Serial RapidIO® (SRIO)	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
	SRIO 3125 LR	3,125
	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
	SRIO_6250_SR	6,250
	SRIO_6250_MR	6,250
	SRIO_6250_LR	6,250

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$t_{OUTPJ_DC}^{(67)}$	Period jitter for dedicated clock output in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	175	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	17.5	mUI (p-p)
$t_{FOUTPJ_DC}^{(67)}$	Period jitter for dedicated clock output in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	$250^{(68)}, 175^{(69)}$	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	$25^{(68)}, 17.5^{(69)}$	mUI (p-p)
$t_{OUTCCJ_DC}^{(67)}$	Cycle-to-cycle jitter for dedicated clock output in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	175	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	17.5	mUI (p-p)
$t_{FOUTCCJ_DC}^{(67)}$	Cycle-to-cycle jitter for dedicated clock output in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	$250^{(68)}, 175^{(69)}$	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	$25^{(68)}, 17.5^{(69)}$	mUI (p-p)
$t_{OUTPJ_IO}^{(67)(70)}$	Period jitter for clock output on a regular I/O in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
$t_{FOUTPJ_IO}^{(67)(68)(70)}$	Period jitter for clock output on a regular I/O in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
$t_{OUTCCJ_IO}^{(67)(70)}$	Cycle-to-cycle jitter for clock output on a regular I/O in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
$t_{FOUTCCJ_IO}^{(67)(68)(70)}$	Cycle-to-cycle jitter for clock output on a regular I/O in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)

⁽⁶⁷⁾ Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Memory Output Clock Jitter Specification for Arria V Devices table.

⁽⁶⁸⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05–0.95 must be ≥ 1000 MHz.

⁽⁶⁹⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be ≥ 1200 MHz.

⁽⁷⁰⁾ External memory interface clock output jitter specifications use a different measurement method, which are available in Memory Output Clock Jitter Specification for Arria V Devices table.

Figure 1-9: SPI Master Timing Diagram

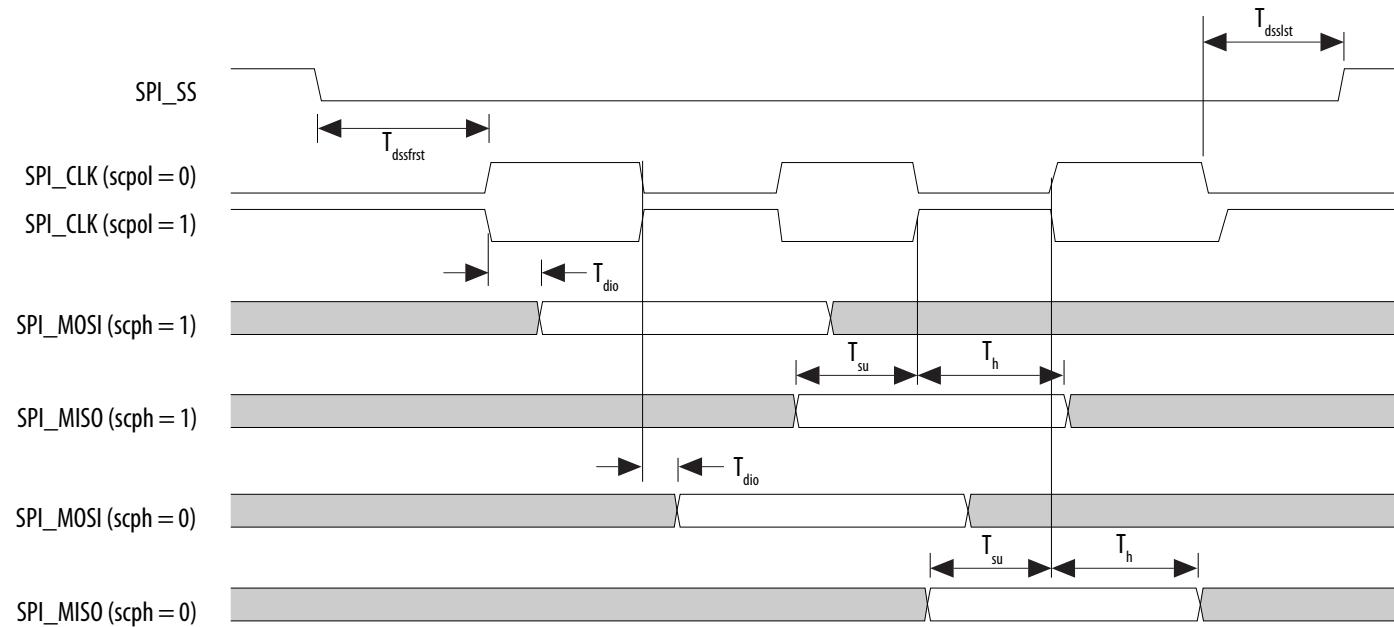


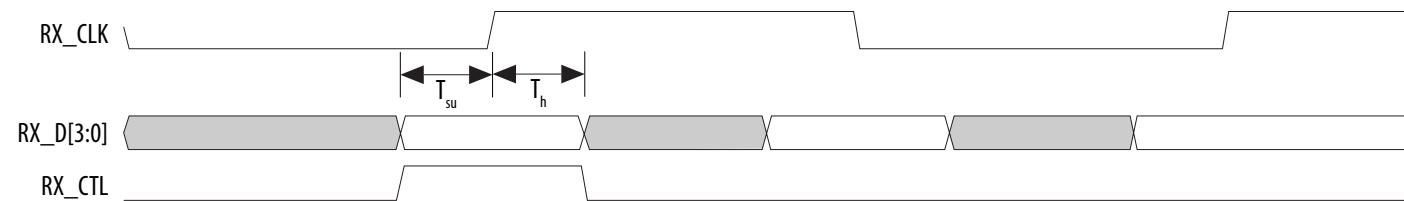
Table 1-53: SPI Slave Timing Requirements for Arria V Devices

The setup and hold times can be used for Texas Instruments SSP mode and National Semiconductor Microwire mode.

Symbol	Description	Min	Max	Unit
T_{clk}	CLK clock period	20	—	ns
T_s	MOSI Setup time	5	—	ns
T_h	MOSI Hold time	5	—	ns
T_{suss}	Setup time SPI_SS valid before first clock edge	8	—	ns
T_{hss}	Hold time SPI_SS valid after last clock edge	8	—	ns
T_d	MISO output delay	—	6	ns

Table 1-57: RGMII RX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Unit
T_{clk} (1000Base-T)	RX_CLK clock period	—	8	ns
T_{clk} (100Base-T)	RX_CLK clock period	—	40	ns
T_{clk} (10Base-T)	RX_CLK clock period	—	400	ns
T_{su}	RX_D/RX_CTL setup time	1	—	ns
T_h	RX_D/RX_CTL hold time	1	—	ns

Figure 1-14: RGMII RX Timing Diagram**Table 1-58: Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices**

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	MDC clock period	—	400	—	ns
T_d	MDC to MDIO output data delay	10	—	20	ns
T_s	Setup time for MDIO data	10	—	—	ns
T_h	Hold time for MDIO data	0	—	—	ns

FPP Configuration Timing

DCLK-to-DATA[] Ratio (r) for FPP Configuration

Fast passive parallel (FPP) configuration requires a different DCLK-to-DATA[] ratio when you turn on encryption or the compression feature.

Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the DATA[] rate in byte per second (Bps) or word per second (Wps). For example, in FPP $\times 16$ where the r is 2, the DCLK frequency must be 2 times the DATA[] rate in Wps.

Table 1-65: DCLK-to-DATA[] Ratio for Arria V Devices

Configuration Scheme	Encryption	Compression	DCLK-to-DATA[] Ratio (r)
FPP (8-bit wide)	Off	Off	1
	On	Off	1
	Off	On	2
	On	On	2
FPP (16-bit wide)	Off	Off	1
	On	Off	2
	Off	On	4
	On	On	4

FPP Configuration Timing when DCLK-to-DATA[] = 1

When you enable decompression or the design security feature, the DCLK-to-DATA[] ratio varies for FPP $\times 8$ and FPP $\times 16$. For the respective DCLK-to-DATA[] ratio, refer to the DCLK-to-DATA[] Ratio for Arria V Devices table.

Table 1-66: FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μs

Term	Definition
JTAG timing specifications	<p>JTAG Timing Specifications</p> <p>The diagram illustrates the timing relationships between four JTAG signals over time. The signals are represented by horizontal lines with vertical markers indicating specific points in time.</p> <ul style="list-style-type: none">TMS: A signal that changes state at regular intervals.TDI: A signal that changes state at the same regular intervals as TMS.TCK: A signal that changes state at a slower rate than TMS and TDI, defining the clock edges for the other signals.TDO: A signal that changes state at the same regular intervals as TMS and TDI, representing the output data. <p>Key timing intervals labeled in the diagram include: - t_{JCP}: Time from the start of a TMS transition to the start of the next TMS transition. - t_{JCH}: Time from the start of a TMS transition to the start of a TDI transition. - t_{JCL}: Time from the start of a TDI transition to the start of the next TMS transition. - t_{JPSU}: Time from the start of a TCK transition to the start of the next TCK transition. - t_{JPH}: Time from the start of a TCK transition to the start of a TDO transition. - t_{JPZX}: Time from the start of a TDO transition to the start of the next TDO transition. - t_{JPCO}: Time from the start of a TDO transition to the start of the next TCK transition. - t_{JPXZ}: Time from the start of a TDO transition to the start of the next TDO transition.</p>

Term	Definition					
PLL specifications	<p>Diagram of PLL specifications</p> <p>Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.</p>					
R_L	Receiver differential input discrete resistor (external to the Arria V device).					
Sampling window (SW)	<p>Timing diagram—The period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position in the sampling window, as shown:</p> <p>Bit Time</p> <table border="1"> <tr> <td>0.5 x TCCS</td> <td>RSKM</td> <td>Sampling Window (SW)</td> <td>RSKM</td> <td>0.5 x TCCS</td> </tr> </table>	0.5 x TCCS	RSKM	Sampling Window (SW)	RSKM	0.5 x TCCS
0.5 x TCCS	RSKM	Sampling Window (SW)	RSKM	0.5 x TCCS		

Date	Version	Changes
January 2015	2015.01.30	<ul style="list-style-type: none">• Updated the description for $V_{CC_AUX_SHARED}$ to “HPS auxiliary power supply” in the following tables:<ul style="list-style-type: none">• Absolute Maximum Ratings for Arria V Devices• HPS Power Supply Operating Conditions for Arria V SX and ST Devices• Added statement in I/O Standard Specifications: You must perform timing closure analysis to determine the maximum achievable frequency for general purpose I/O standards.• Updated the conditions for transceiver reference clock rise time and fall time: Measure at ± 60 mV of differential signal. Added a note to the conditions: REFCLK performance requires to meet transmitter REFCLK phase noise specification.• Updated the description in Periphery Performance Specifications to mention that proper timing closure is required in design.• Updated HPS Clock Performance main_base_clk specifications from 525 MHz (for -I3 speed grade) and 462 MHz (for -C4 speed grade) to 400 MHz.• Updated HPS PLL VCO maximum frequency to 1,600 MHz (for -C5, -I5, and -C6 speed grades), 1,850 MHz (for -C4 speed grade), and 2,100 MHz (for -I3 speed grade).• Changed the symbol for HPS PLL input jitter divide value from NR to N.• Removed “Slave select pulse width (Texas Instruments SSP mode)” parameter from the following tables:<ul style="list-style-type: none">• SPI Master Timing Requirements for Arria V Devices• SPI Slave Timing Requirements for Arria V Devices• Added descriptions to USB Timing Characteristics section in HPS Specifications: PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.• Added HPS JTAG timing specifications.• Updated FPGA JTAG timing specifications note as follows: A 1-ns adder is required for each V_{CCIO} voltage step down from 3.0 V. For example, $t_{JPCO} = 13$ ns if V_{CCIO} of the TDO I/O bank = 2.5 V, or 14 ns if it equals 1.8 V.• Updated the value in the V_{ICM} (AC Coupled) row and in note 6 from 650 mV to 750 mV in the Transceiver Specifications for Arria V GT and ST Devices table.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle.

For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Table 2-4: Maximum Allowed Overshoot During Transitions for Arria V GZ Devices

Symbol	Description	Condition (V)	Overshoot Duration as % @ $T_J = 100^\circ\text{C}$	Unit
Vi (AC)	AC input voltage	3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Recommended Operating Conditions

Table 2-5: Recommended Operating Conditions for Arria V GZ Devices

Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum ⁽¹¹⁴⁾	Typical	Maximum ⁽¹¹⁴⁾	Unit
V_{CC}	Core voltage and periphery circuitry power supply ⁽¹¹⁵⁾	—	0.82	0.85	0.88	V

⁽¹¹⁴⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹¹⁵⁾ The V_{CC} core supply must be set to 0.9 V if the Partial Reconfiguration (PR) feature is used.

I/O Standard Specifications

The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.

Table 2-16: Single-Ended I/O Standards for Arria V GZ Devices

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
LV-TTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVC-MOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	$V_{CCIO} - 0.2$	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	0.45	$V_{CCIO} - 0.45$	2	-2
1.5 V	1.425	1.5	1.575	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2
1.2 V	1.14	1.2	1.26	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2

Table 2-17: Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Arria V GZ Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$

I/O Standard	V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V _{CCIO} /2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V _{CCIO} /2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 × V _{CCIO}	0.5 × V _{CCIO}	0.53 × V _{CCIO}	—	V _{CCIO} /2	—
HSUL-12	1.14	1.2	1.3	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	—	—	—

Table 2-18: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V GZ Devices

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{ol} (mA)	I _{oh} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	V _{TT} - 0.603	V _{TT} + 0.603	6.7	-6.7

Table 2-19: Differential SSTL I/O Standards for Arria V GZ Devices

I/O Standard	V _{CCIO} (V)			V _{SWING(DC)} (V)		V _{X(AC)} (V)			V _{SWING(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.2	—	V _{CCIO} /2 + 0.2	0.62	V _{CCIO} + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.175	—	V _{CCIO} /2 + 0.175	0.5	V _{CCIO} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	⁽¹²⁷⁾	V _{CCIO} /2 - 0.15	—	V _{CCIO} /2 + 0.15	0.35	—
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	⁽¹²⁷⁾	V _{CCIO} /2 - 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	⁽¹²⁷⁾	V _{CCIO} /2 - 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	—
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	—	V _{REF} - 0.15	V _{CCIO} /2	V _{REF} + 0.15	-0.30	0.30

Table 2-20: Differential HSTL and HSUL I/O Standards for Arria V GZ Devices

I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—

⁽¹²⁷⁾ The maximum value for V_{SWING(DC)} is not defined. However, each single-ended signal needs to be within the respective single-ended limits (V_{IH(DC)} and V_{IL(DC)}).

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Transmitter REFCLK Phase Noise (622 MHz) ⁽¹⁴¹⁾	100 Hz	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	dBc/Hz
	10 kHz	—	—	-100	—	—	-100	dBc/Hz
	100 kHz	—	—	-110	—	—	-110	dBc/Hz
	≥1 MHz	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁴²⁾	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	ps (rms)
R _{REF}	—	—	1800 ±1%	—	—	1800 ±1%	—	Ω

Related Information**Arria V Device Overview**

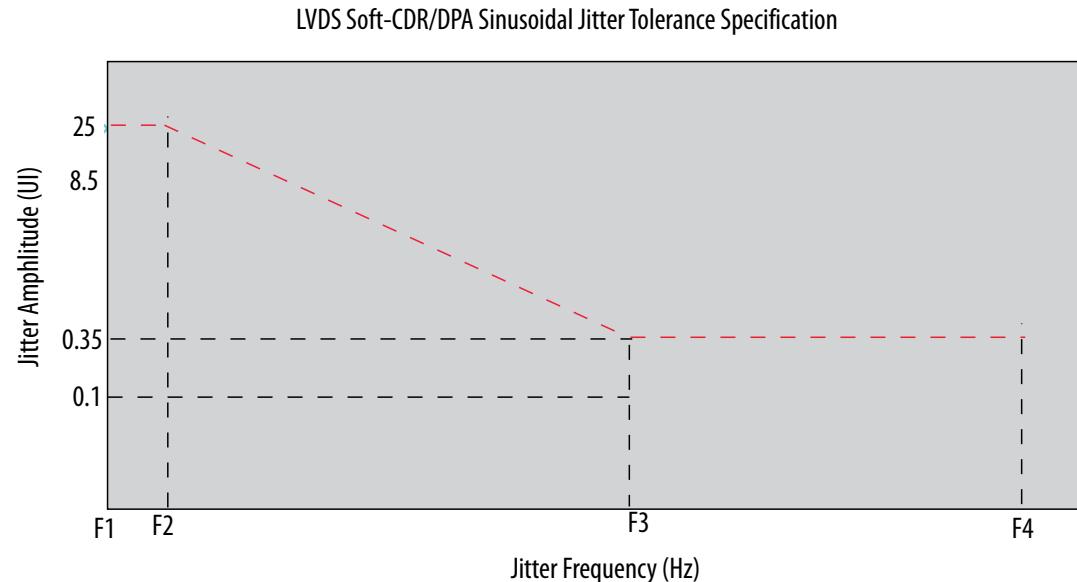
For more information about device ordering codes.

Transceiver Clocks**Table 2-23: Transceiver Clocks Specifications for Arria V GZ Devices**

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

⁽¹⁴¹⁾ To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).

⁽¹⁴²⁾ To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.

Figure 2-4: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate ≥ 1.25 Gbps**Table 2-45: LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate ≥ 1.25 Gbps**

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Date	Version	Changes
June 2016	2016.06.20	<ul style="list-style-type: none">Changed column heading from "Value" to "Maximum" in the "Pin Capacitance for Arria V GZ Devices" table.Changed the minimum supported data rate range values from "1000" to "2000" in the "ATX PLL Specifications for Arria V GZ Devices" table.Added the supported data rates for the following output standards using true LVDS output buffer types in the "High-Speed Clock Specifications for Arria V GZ Devices" table:<ul style="list-style-type: none">True RSRS output standard: data rates of up to 230 MbpsTrue mini-LVDS output standard: data rates of up to 340 Mbps
December 2015	2015.12.16	<ul style="list-style-type: none">Removed the CDR ppm tolerance specification from the "Receiver Specifications for Arria V GZ Devices" table.Removed transmitter rise and fall time specifications from the "Transmitter Specifications for Arria V GZ Devices" table.Changed the .rbf sizes in the "Uncompressed .rbf Sizes for Arria V GZ Devices" table.Added a footnote to the "Transmitter High-Speed I/O Specifications for Arria V GZ Devices" table.
June 2015	2015.06.16	<ul style="list-style-type: none">Changed the conditions for the reference clock rise and fall time and added a note to the condition in the "Reference Clock Specifications for Arria V GZ Devices" table.Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Receiver Specifications for Arria V GZ Devices" table.
January 2015	2015.01.30	<ul style="list-style-type: none">Added 240-Ω to the "OCT Calibration Accuracy Specifications for Arria V GZ Devices" table.Changed the CDR PPM tolerance spec in the "Receiver Specifications for Arria V GZ Devices" table.Added additional max data rate for fPLL in the "Fractional PLL Specifications for Arria V GZ Devices" table.